

SUSS MICROTEC INVESTOR PRESENTATION

April 2018



SUSS MICROTEC AT A GLANCE

- + International high tech equipment provider for the semiconductor mid- and backend industry
- + All major chip manufacturers are clients of ours
- + Global customer base with focus on Asia
- + Production at two major sites in Germany and one in the USA



USA



Germany

Highlights FY 2017

- + Order entry € 200.3 million
- + Sales € 166.5 million
- + EBIT 13.9 million
- + EBIT-margin 8.3%

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 19.5 € million
Sales 26.2 € million
Employees 102

EMEA

Order Entry 40.1 € million
Sales 38.8 € million
Employees 539

ASIA

Order Entry 140.7 € million
Sales 101.1 € million
Employees 138



*Figures refer to the fiscal year 2017

OUR PRODUCT PORTFOLIO

Frontend

Mid- and Backend

**Photomask
Equipment**

Photomask
Cleaning



MaskTrackPro

Lithography

Laser Processing
Equipment



ELP300

Exposure
Systems



Mask Aligner
MA200/300 Gen2



Projection Scanner
DSC300 Gen2

Coaters and
Developers



ACS300 Gen2

Bonder

Wafer Bonding
Equipment



XBC300 Gen2



XB8

WE SUPPORT TECHNOLOGICAL CHANGE

Telecommunications



- Communication
- Mobility
- Networks

Data Processing



- Data processing
- Mobility
- Digitization
- Smart factory

Automotive



- Safety
- Comfort
- Energy efficiency
- Autonomous driving

Portable electronic products are driving component packaging towards new packaging technologies for integrating multiple functions (e.g. memory, analog and passive components: SiP)



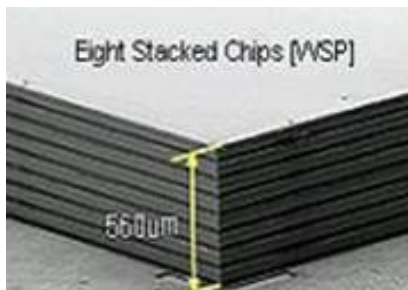
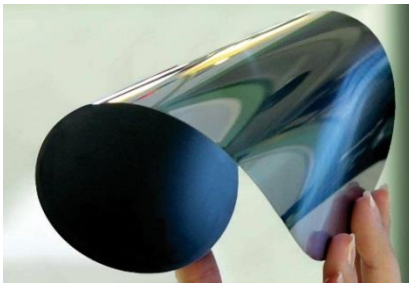
+ **Fan Out Wafer Level Packaging (FOWLP)**

+ **3D- Integration with Thru Silicon Vias (TSV)**

Allows for:

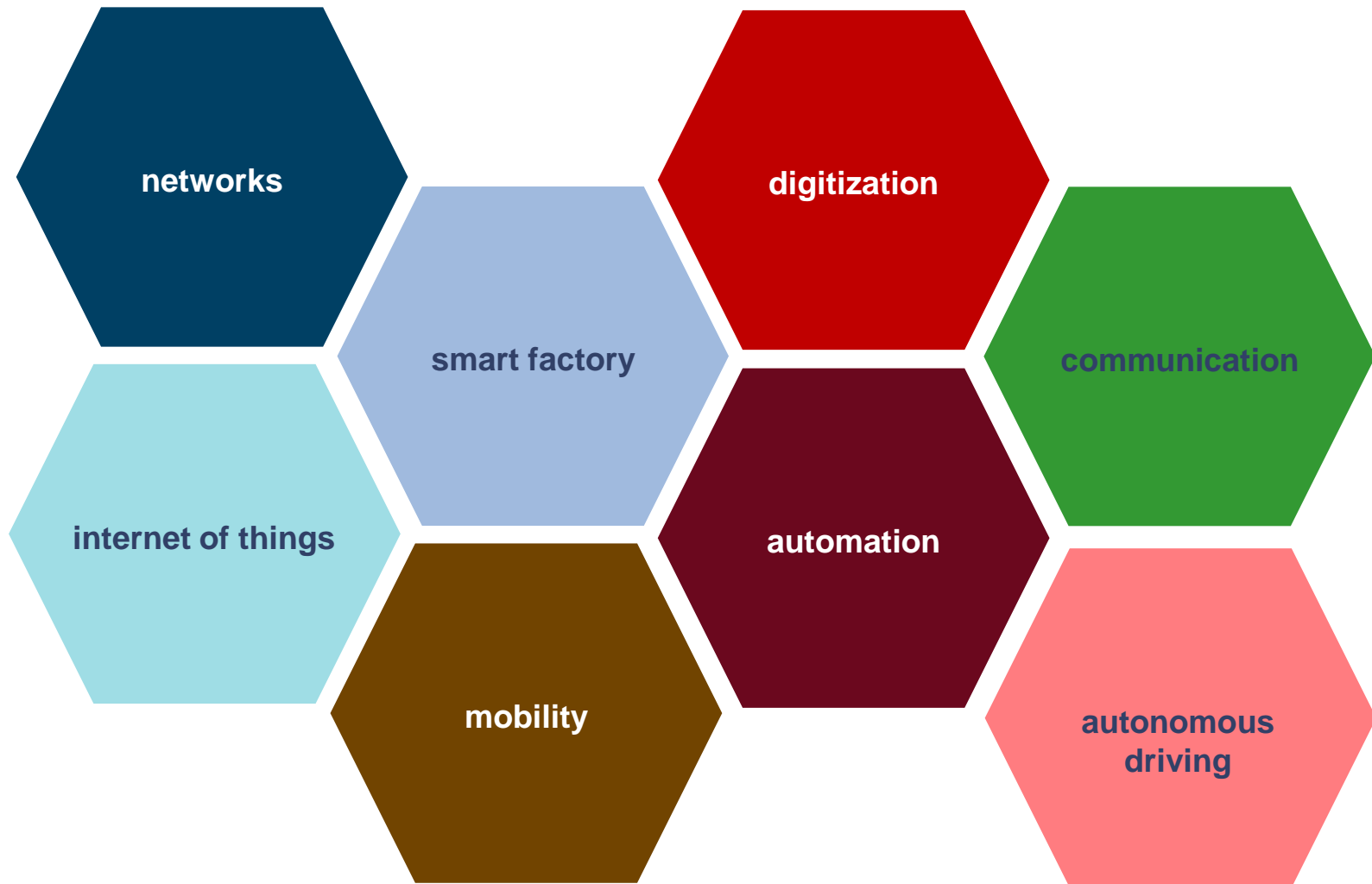
- **Smaller form factors**
- **Multi-die package / SiP**
- **Increased I/O density** (Fine line and space (L/S))
- **Providing high capacity and high bandwidth packages**

This trend will continue.



- + **Since the early 1990s, advanced packaging methods have enabled smaller chip packages:**
 - SUSS was one of the drivers in the introduction of advanced packaging in the 1990s
 - SUSS was a founding member of SECAP (Semiconductor Equipment Consortium for Advanced Packaging)
 - SECAP supported the transition from "wire bonding" to "flip chip bonding"
- + **Today, SUSS supports the transition from 2D to 2.5D and finally to 3D TSV (Thru Silicon Via)**
 - SUSS works with the leading users of 3D TSV technology
 - First pilot lines are installed and will be further optimized
 - SUSS is one of the leading equipment suppliers for this growth area
- + **„Thin wafer handling “ and „temporary bonding“ are major elements of 3D stacking**

GROWTH DRIVERS ARE INTACT

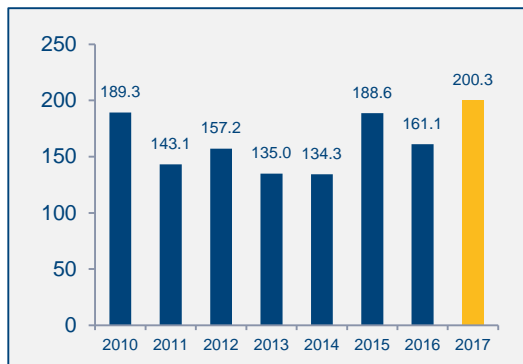


KEY GROUP FIGURES AT A GLANCE FY 2015 - 2017

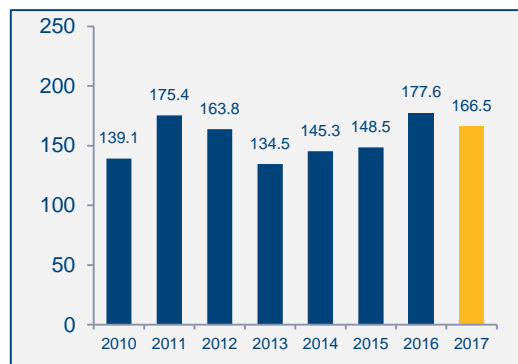
in € million	<i>delta 2017/2016</i>	2017	2016	2015
Order Intake	+24.3%	200.3	161.1	188.6
Order Backlog 12/31	+31.4%	133.4	101.5	117.6
Revenue	-6.2%	166.5	177.6	148.5
EBIT	+25.2%	13.9	11.1	5.0
<i>EBIT in % of Sales</i>	<i>+2.1%pts</i>	<i>8.3%</i>	<i>6.3%</i>	<i>3.4%</i>
Earnings after tax	+34.0%	6.7	5.0	0.2
EPS in €	+34.2%	0.35	0.26	0.01
Free Cash Flow	--	2.9	-9.1	1.3
Net Cash	+6.1%	33.0	31.1	40.0
Employees 12/31	+9.6%	779	711	698

LONG TERM BUSINESS DEVELOPMENT

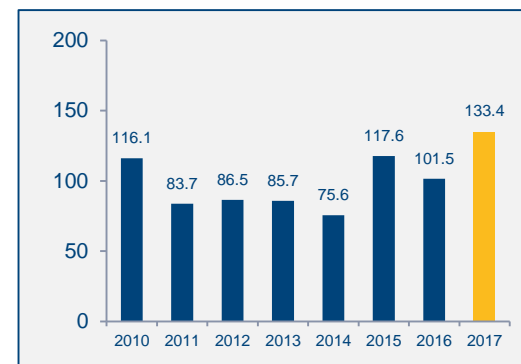
Order Entry in € million



Sales in € million



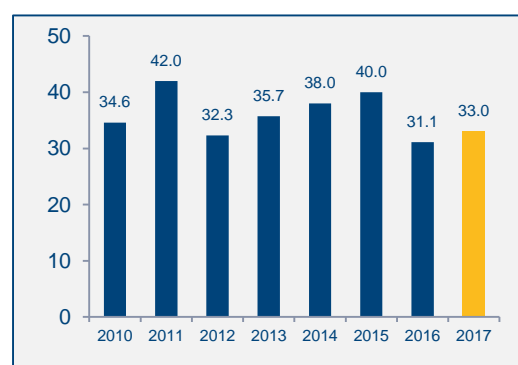
Order Backlog in € million



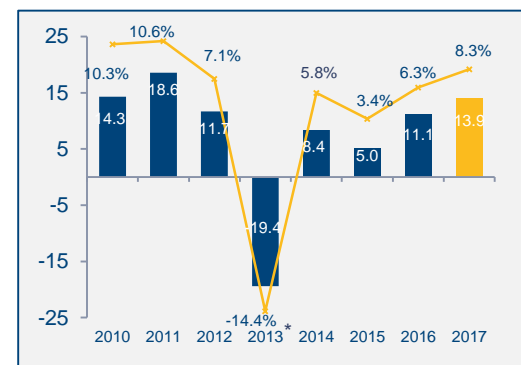
Free Cash Flow** in € million



Net Cash in € million



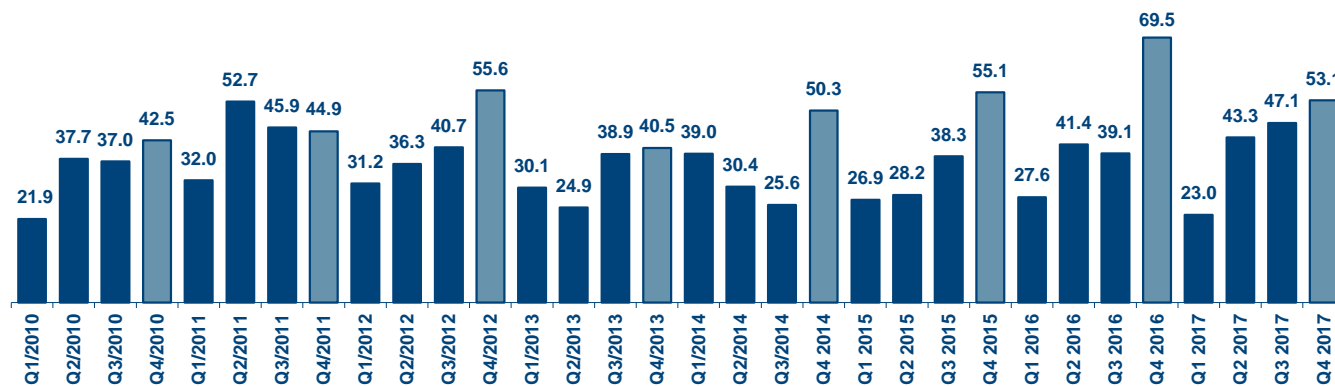
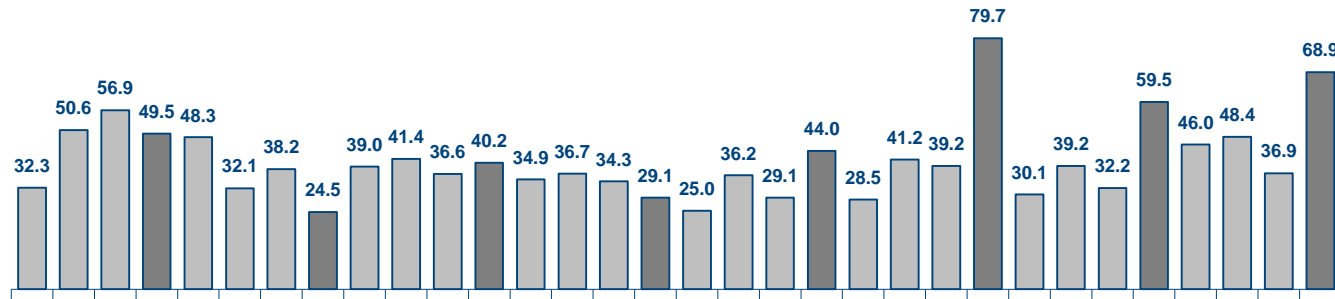
EBIT in € million



* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

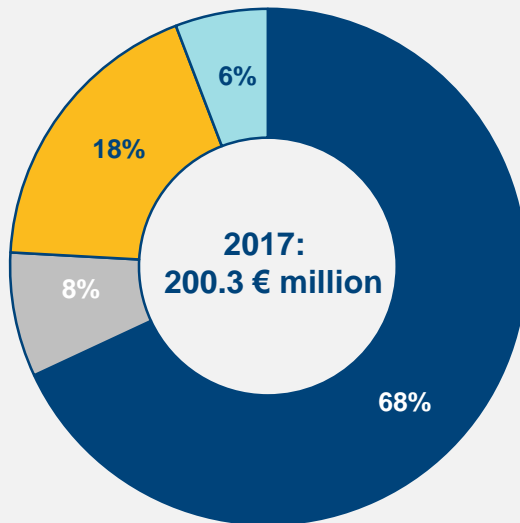
** FCF = operating CF + CF from investments + changes in securities holdings

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



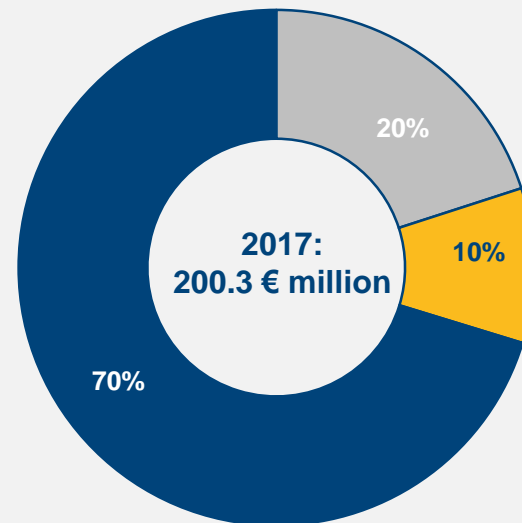
ORDER ENTRY BY SEGMENT AND REGION FULL YEAR 2017

Segments



- Lithography
- Fotomask Equipment
- Bonder
- Others

Regions



- EMEA
- North America
- Asia/Pacific

SEGMENTS, ORDER ENTRY AND SALES FULL YEAR 2017

Divisions

Photomask Equipment

Photomask Cleaning
Equipment

Order Entry: 15.7 € million
Sales: 19.7 € million
EBIT: 5.1 € million
EBIT-Margin: 25.9%
Adj. EBIT-Margin: 15.7%*
**€ -2m licence agreement*

Lithography

Laser
Processing
Equipment

Exposure
Systems

Coaters and
Developers

Order Entry: 136.2 € million
Sales: 112.8 € million
EBIT: 6.3 € million
EBIT-Margin: 5.6%
Adj. EBIT-Margin: 14.5%*
**€ +10m losses Photonic Systems*

Bonder

Wafer Bonding
Equipment

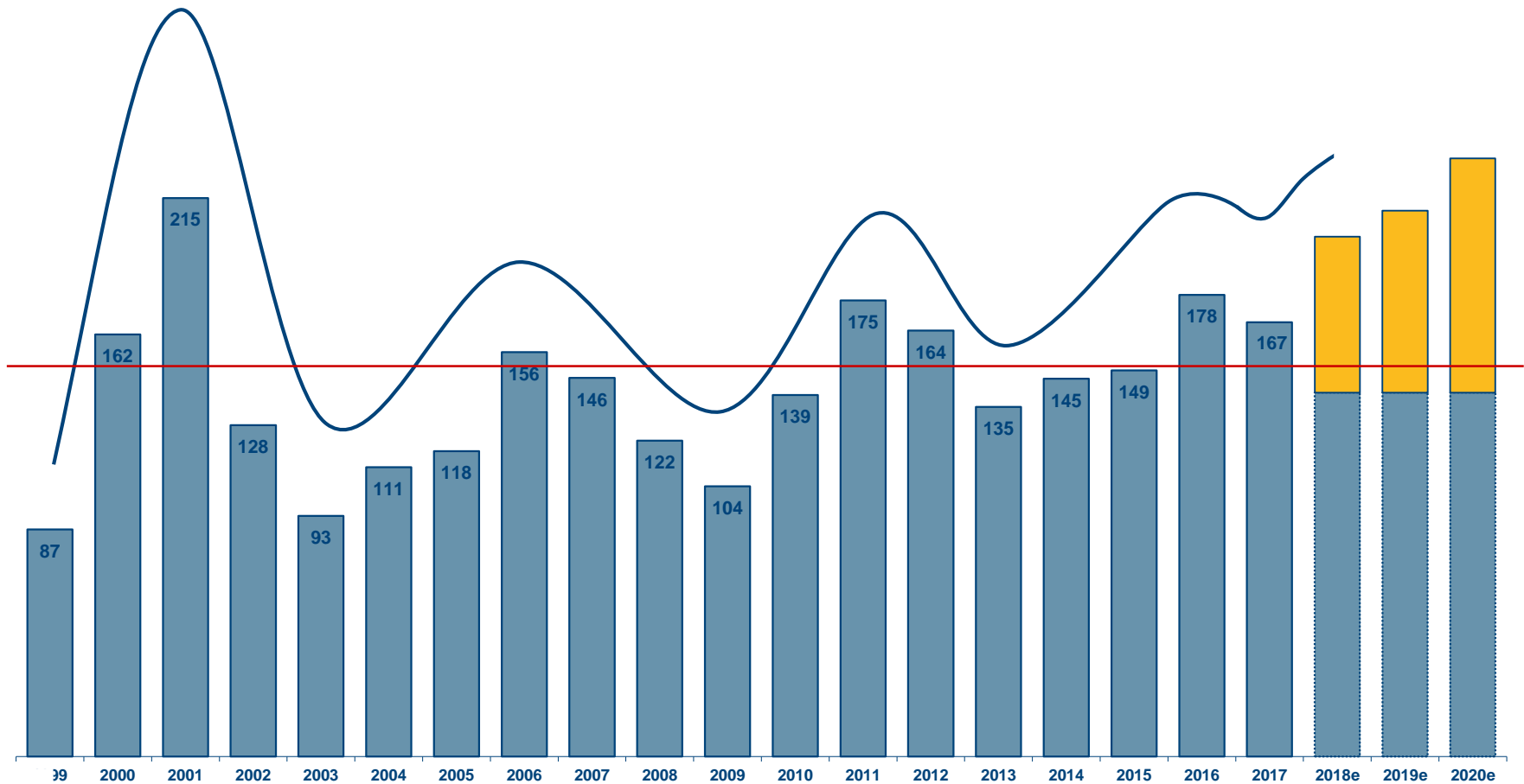
Order Entry: 36.7 € million
Sales: 22.1 € million
EBIT: 3.3 € million
EBIT-Margin: 14.9%
Adj. EBIT-Margin: 10.4%*
**€ -1m extraordinary margin perm. bonder*

SÜSS MicroTec Group FY 2017*

Order Entry: 200.3 € million
Sales: 166.5 € million
EBIT: 13.9 € million
EBIT margin: 8.3%
Adj. EBIT-Margin: 12.6%

* Including Others

LONG TERM SALES DEVELOPMENT IN € MILLION



Average sales level 1999 – 2017: appr. € 150 million



+ Fiscal year 2018: **Sales € 195 million – € 205 million**
 EBIT 8.5% – 10.0%

+ 1st half 2018: **Order entry € 70 - 80 million**



- + Gartner expects the semiconductor market to grow by 7.5% in 2018 after 22.2% in 2017
- + This would mark a new record sales level of USD 451 billion for the semiconductor industry in 2018
- + Market growth is driven by automotive and industrial applications as well as memory chips and the internet of things
- + Semi expects a market growth of +7.5 % in the semiconductor-equipment industry in 2018 after 35.6% in 2017
- + Wafer fab equipment incl. Wafer-level packaging grew by +17.9% in 2017 (according to Gartner)
- + Yole expects the MEMS-market to grow by +16.7% (CAGR) from 2016 to 2022(unit growth)



WE ARE SÜSS MICROTec – BACK UP

Contact

Franka Schielke

Tel.: +49 89-32007- 161

Fax.: +49 89-32007- 451

Email: franka.schielke@suss.com

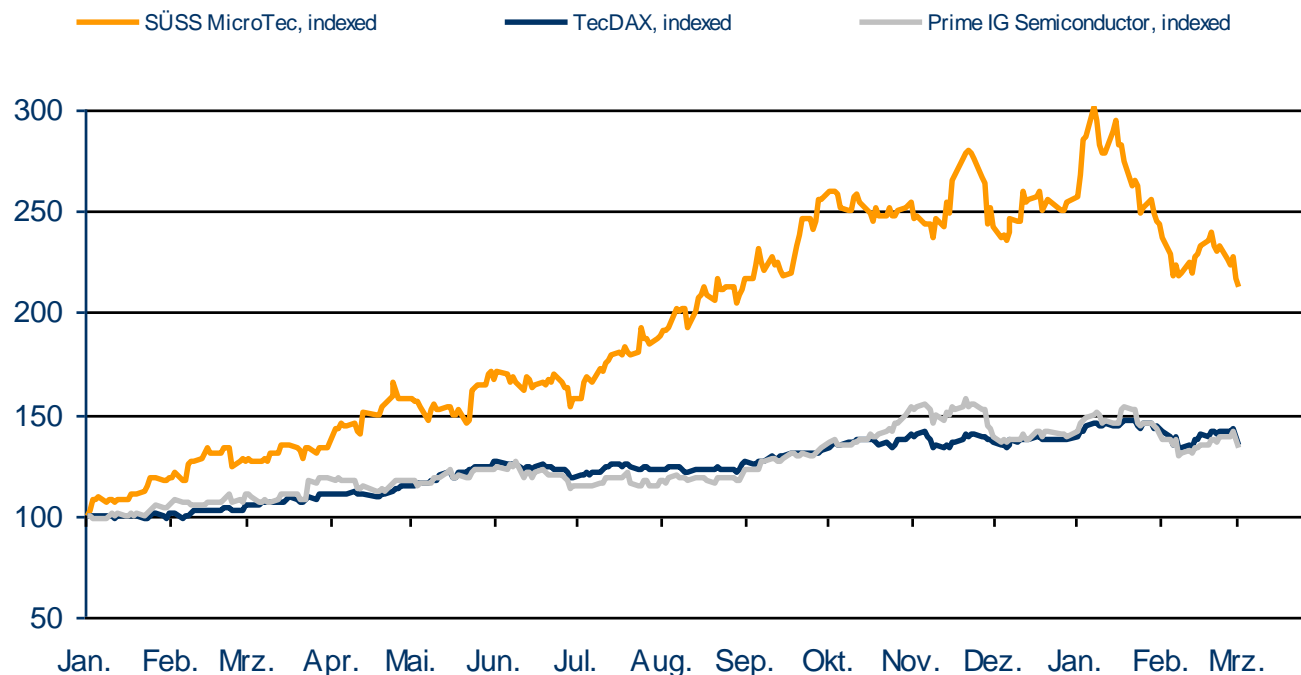
SÜSS MicroTec SE
Schleissheimer Strasse 90
85748 Garching
Germany
www.suss.com

Financial Calendar 2018

Quarterly Report 2018	3 May
Annual General Meeting 2018, Munich	6 Jun
Interim Report 2018	3 Aug
Nine-month Report 2018	7 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2017: 6.54 €)

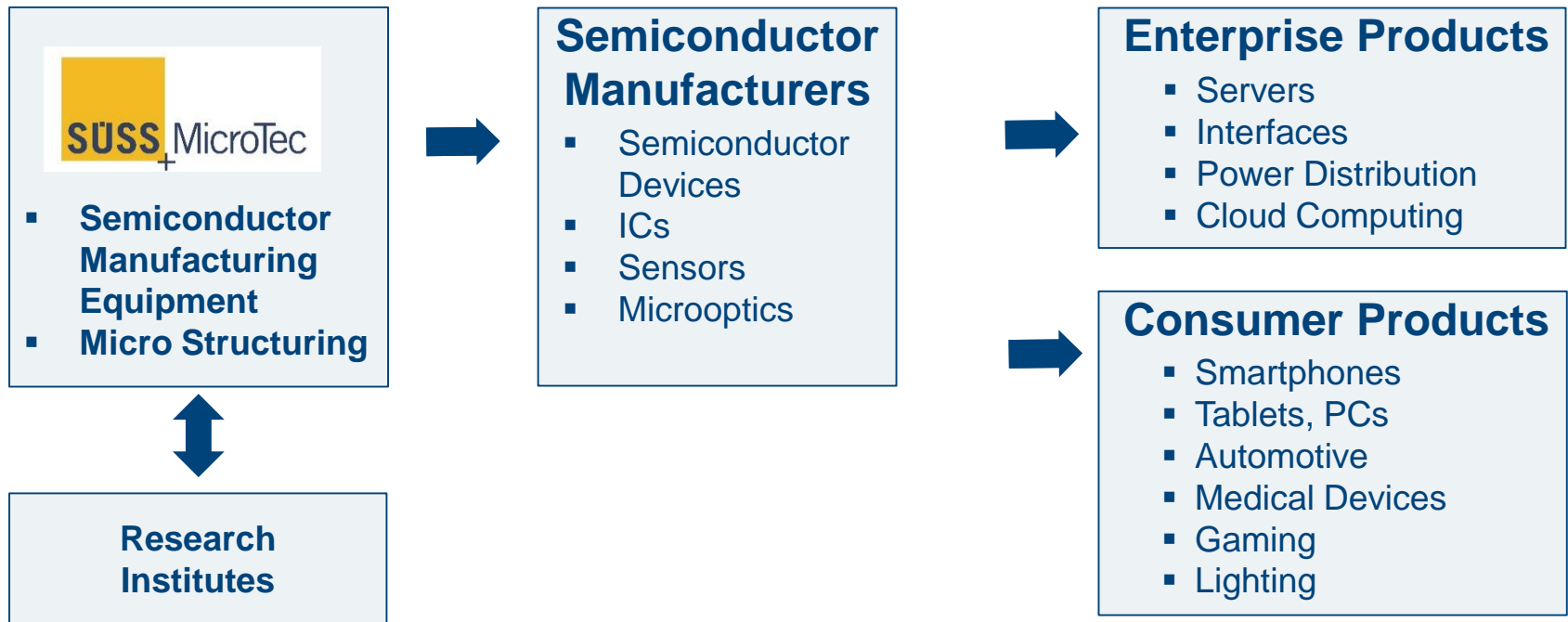


Major Shareholders > 3%:

Kempen Oranje
Universal-Investment
Luxunion
Janus Henderson Group
Sycomore Asset Man.
Oddo BHF
Lupus Alpha
Hansa Invest
Dimensional Funds

Average daily trading volume January 2017 – March 2018: ~ 118.000

SUSS MICROTEC IN THE VALUE CHAIN

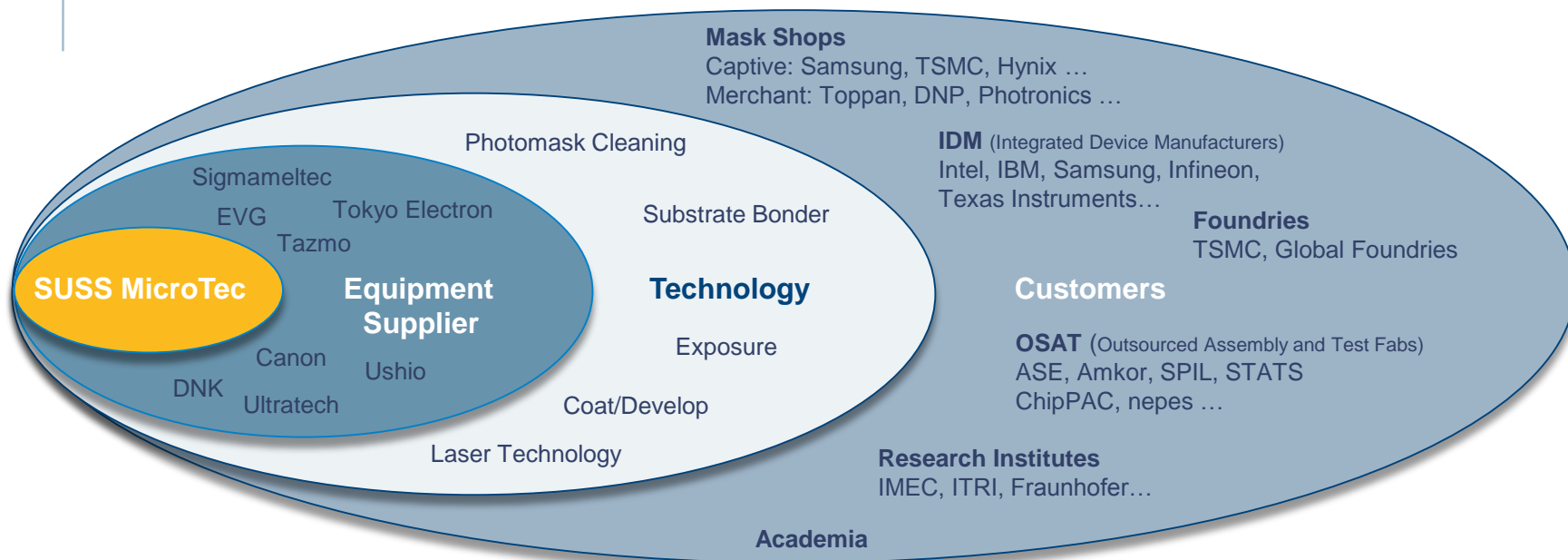


+ SUSS MicroTec:

- Key player in leading edge semiconductor manufacturing equipment
- Developer of highly innovative process solutions

+ Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment

MAIN COMPETITORS AND PEER GROUP



Peer Group

BE Semiconductor:

equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy

Veeco/UTEC:

steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)

Kulicke & Soffa:

design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)

Rudolph Tech:

equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)

EV Group:

equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.